# Three Lectures on Interfacial Fracture Mechanics: ESPCI, October 2012

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- **Lecture #1:** Overview. Crack tip fields, Basic solutions, Interface toughness and thin film delamination as an illustration
- **Lecture #2:** Special elastic mismatch effects, Origins of mixed mode toughness dependence, Buckling delamination, Thermal barrier coating delamination & interface toughness
- **Lecture #3:** Initiation of delamination vs. steady-state delamination in thin films & 3D effects, Kinking of a crack out of an interface. Cracks approaching an interface: penetration vs. kinking. Various applications.

References will included on the slides.

My own papers are available on my website http://www.seas.harvard.edu/hutchinson These paper will be referenced in the format (year-paper#), e.g., (2012-3)

# VARIOUS KINDS OF DELAMINATION CRACKING WE WILL CONSIDER



# **Crack Tip Fields for Bilayer Interface Joining Isotropic Elastic Solids** (1992-2; pg.72) **Dundurs parameters** (2D elasticity for bilayers)

With 
$$\mu = \frac{E}{2(1+\nu)}$$
,  
plane strain:  $\alpha_D = \frac{\overline{E}_1 - \overline{E}_2}{\overline{E}_1 + \overline{E}_2}$ ,  $\beta_D = \frac{1}{2} \frac{\mu_1(1-2\nu_2) - \mu_2(1-2\nu_1)}{\mu_1(1-\nu_2) + \mu_2(1-\nu_1)}$ ,  $\overline{E} = \frac{E}{(1-\nu^2)}$   
plane stress:  $\alpha_D = \frac{\mu_1(1+\nu_1) - \mu_2(1+\nu_2)}{\mu_1(1+\nu_1) + \mu_2(1+\nu_2)}$ ,  $\beta_D = \frac{1}{2} \frac{\mu_1(1+\nu_1)(1-\nu_2) - \mu_2(1+\nu_2)(1-\nu_1)}{\mu_1(1+\nu_1) + \mu_2(1+\nu_2)}$ ,  
 $\alpha \equiv \alpha_D$   
 $\beta \equiv \beta_D$   
 $\beta \equiv \beta_D$   
 $\beta = \beta_D$   
 $\beta_{1,Cu}$   
 $\beta_{1,$ 

FIG. 6. Values of Dundurs' parameters in plane strain for selected combinations of materials.

Crack Tip Fields for Bilayer Interface Joining Isotropic Elastic Solids (1992-2; pg.72)

To make life simpler, most of our discussion will take  $\beta = 0 \Rightarrow \varepsilon = 0$  but  $\alpha \neq 0$ For these cases, the singular stress fields at the tip are identical to those for a homogeneous solid

Pg. 4

**Some Basic Bilayer Solutions:** 

1) crack on an interface between two half spaces: reference cited in (1992-2)

$$K_{1} + iK_{2} = (\sigma_{22}^{\infty} + i\sigma_{12}^{\infty})(1 + 2i\varepsilon)(\pi a)^{1/2}(2a)^{-i\varepsilon}$$

$$\sigma_{22} = \operatorname{Re}[Kr^{i\varepsilon}](2\pi r)^{-1/2}, \quad \sigma_{12} = \operatorname{Im}[Kr^{i\varepsilon}](2\pi r)^{-1/2}$$

$$\beta = 0 \Rightarrow \quad (K_{1}, K_{2}) = (\sigma_{22}^{\infty}, \sigma_{12}^{\infty})\sqrt{\pi a},$$

$$(\sigma_{22}, \sigma_{12}) = (K_{1}, K_{2})\frac{1}{\sqrt{2\pi r}}, \quad (\delta_{2}, \delta_{1}) = (K_{1}, K_{2})\frac{8}{E_{*}}\sqrt{\frac{r}{2\pi}} \quad (r/a <<1)$$

$$Valid for arbitrary large electic migmetch with  $\alpha \neq 0$ ,  $\beta = 0$$$

Valid for arbitrary large elastic mismatch with  $\alpha \neq 0$  &  $\beta = 0$ 

For  $\beta \neq 0$ ,  $\varepsilon = \frac{1}{2\pi} \ln\left(\frac{1-\beta}{1+\beta}\right)$ , near the crack tip:  $\delta_2 + i\delta_1 = \frac{8}{(1+2i\varepsilon)\cosh(\pi\varepsilon)} \frac{(K_1 + iK_2)}{E_*} \left(\frac{r}{2\pi}\right)^{1/2} r^{i\varepsilon}$ 1.1  $\delta_2 + i\delta_1 = \frac{8(\sigma_{22}^{\infty} + i\sigma_{12}^{\infty})\sqrt{\pi a}}{\cosh(\pi\varepsilon)F} \sqrt{\frac{r}{2\pi}} \left(\frac{r}{2\pi}\right)^{i\varepsilon}$ 1.05  $-\frac{\delta_2(r)}{\delta_2^0(r)}$ For  $\sigma_{12}^{\infty} = 0$ , 0.95  $\delta_2(r) = \frac{8}{E_{\pi}} \sqrt{\sigma_{22}^{\infty} \pi a} \sqrt{\frac{r}{2\pi}} \times \frac{\cos(\varepsilon \ln(r/2a))}{\cosh(\pi\varepsilon)}$  $\beta = 0, 0.05, 0.1, 0.15, 0.2$ 0.9  $\equiv \delta_2^0(r) \times \frac{\cos(\varepsilon \ln(r/2a))}{\cosh(\pi\varepsilon)}$ 0.85 -r/a 0.8

For most problems one can take  $\beta=0$  to make life simple!!



Pg. 5

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## Some Basic Bilayer Solutions:

# 2) Crack on an interface between two layers under general loading (1990-1)

The general solution has been obtained and tabulated in (1990-1) see this reference or (1992-2) for full details & numerical tables.

The energy release rate, G, can be obtained by elementary energy accounting because of steady-state character of the problem.

$$G = \frac{1}{2\bar{E}_1} \left( \frac{P_1^2}{h} + 12\frac{M_1^2}{h^3} \right) + \frac{1}{2\bar{E}_2} \left( \frac{P_2^2}{H} + 12\frac{M_2^2}{H^3} - \frac{P_3^2}{Ah} - \frac{M_1^2}{H^4} \right)$$

$$K_{1} + iK_{2} = h^{-i\epsilon} \left(\frac{1-a}{1-\beta^{2}}\right)^{1/2} \left(\frac{P}{\sqrt{2hU}} - ie^{i\gamma} \frac{M}{\sqrt{2h^{3}V}}\right) e^{i\omega}$$

Everything is the above formula is given by simple formulas (1992-1) except  $\omega(\alpha, \beta, \eta), \quad \eta = h/H$ which is plotted & tabulated,



Interface

#### An illustration of the energy release rate calculation for a steady-state problem Pg. 7



# Some special cases of bilayers (1992-2)

Homogeneous material  ${\cal G}_{{}_{\rm II}}$ Specimen Ψ  $G_1$  $E_L \equiv \overline{E}$  $G_I = K_1^2 / \overline{E}$ М  $\frac{12M^2}{E_Lh^3}$  $0^{\circ}$ Ì h 0  $G_{II} = K_2^2 / \overline{E}$ a) ĥ М  $G = G_I + G_{II}$ 9M<sup>2</sup> E<sub>L</sub>h<sup>3</sup> ‡h  $\tan\psi = \frac{K_2}{K_1}$ b) 0 **-90**° İh  $\psi = 0^0 \Leftrightarrow \text{mode I}$  $\psi = \pm 90^{\circ} \Leftrightarrow \text{mode II}$ 3M<sup>2</sup> E<sub>L</sub>h <sup>3</sup> 9M <sup>2</sup> 4E<sub>L</sub>h <sup>3</sup> Μ )м 36.9° C)  $K_{II}$  $K_I$ 3P<sup>2</sup> 4E<sub>L</sub>h <u>Р<sup>2</sup></u> Е<sub>1</sub> h 53.1° → P d) P-

Crack on an interface between two materials of equal thickness (1992-2)



We will revisit this example later

Pg. 9

### Some special cases of bilayers (1987-1), (1992-2)



 $d / h = 0.13 \Leftrightarrow \text{mode I}$ 

Pg. 10

Pg. 11 Some special cases of bilayers: film on an infinitely deep substrate (1992-2)



#### An example: Uniformly stressed thin film on deep substrate



 $G = \frac{\sigma^2 h}{2\overline{E_1}} \qquad \beta = 0 \qquad \beta = 0$   $K_I = \sigma \sqrt{h} \cos \omega / \sqrt{2} = 0.434 \sigma \sqrt{h}, \quad K_{II} = \sigma \sqrt{h} \sin \omega / \sqrt{2} = 0.558 \sigma \sqrt{h} / \sqrt{2} \quad (\psi = 52.1^{\circ})$ This applies for **tensile stress** in film ( $\sigma > 0$ ) with  $K_I > 0$ :

If the film stress is **compressive** ( $\sigma < 0$ ), the formula predicts  $K_I < 0$  the formula is not valid--the problem is approximately mode II

Closed, mode II crack. Only valid if friction is neglected.  $\sigma < 0$ :  $K_I = 0$ ,  $K_{II} = -0.707 \sigma \sqrt{h}$ 

# Mode I cracking in substrate driven by tensile stresses in film or coating (1989-2, 1992-2)



Neglecting elastic mismatch the basic solution gives

$$K_{I} = \frac{\sigma h}{\sqrt{2d}} \left( \cos \omega + \sqrt{3} \left( (d-h)/d \right) \sin \omega \right)$$
$$K_{II} = \frac{\sigma h}{\sqrt{2d}} \left( \sin \omega - \sqrt{3} \left( (d-h)/d \right) \cos \omega \right)$$



*pg*.13

Depth of mode I crack

$$K_{II} = 0$$
 with  $\omega = 52.1^{\circ} \Rightarrow \frac{d}{h} = 3.86$ ,  $K_I = 0.586 \sigma \sqrt{h}$  and  $G = 0.343 \sigma^2 h / \overline{E}$ 

Compare with mixed mode delamination along interface

$$K_I = 0.434 \sigma \sqrt{h}, K_I = 0.556 \sigma \sqrt{h}$$
 and  $G = 0.50 \sigma^2 h / \overline{E}$ 

Substrate delamination as mode I crack propagation is observed in systems where the interface is relatively tough and the substrate is brittle. The stress in the film or coating must be in tension. No mode I path exists in the substrate if the stress is compression.

See Drory, Thouless & Evans (1988) for experimental observations for metal/glass systems.



For a mode I crack to exist within layer with linear stress variation:

$$\sigma_0 > 0 \quad \& \qquad \implies \qquad d = 0.817 \frac{\sigma_0}{d\sigma/dy} \& \qquad G = 0.353 \frac{\sigma_0}{\overline{E} \, d\sigma/dy}$$

*pg*.14

3

Pg. 15  $K_I, K_{II}$ Interface toughness—the role of mode mix (1992-2) **Experimental finding:** The energy release rate required to propagate a crack along an interface generally depends on the mode mix, often with  $\int_{40} \Gamma_{\rm C}(\psi) (Jm^{-2})$ larger toughness the larger the mode II component Interface Toughness:  $\Gamma_{\rm C}(\psi)$ Propagation condition:  $G = \Gamma_{C}(\psi)$ 30A phenomenological interface toughness law 20 $\lambda \cong 0.1$  $\Gamma_{C}(\psi) = \Gamma_{IC} \left( 1 + \tan^{2}((1 - \lambda)\psi) \right)$ 10.  $\Gamma_{IIC}/\Gamma_{IC}$  $\Gamma_{c}(\psi)$ 140 14  $-90^{\circ}$ 12  $45^{0}$ 15 45<sup>0</sup>  $^{0}00'$ 10 40  $\lambda = .1, .2, .5, 1$ 45 V 8 10 Liechti & Chai (1992) data for an epoxy/glass 6 interface. 5 4  $\lambda = 1 \Longrightarrow$  no mode dependence 2 n 0  $^{0.8}\lambda$  $\lambda << 1 \Rightarrow$  significant mode dependence 0.2 0.4 0 0.6  $\psi$  in degrees 20 80 0